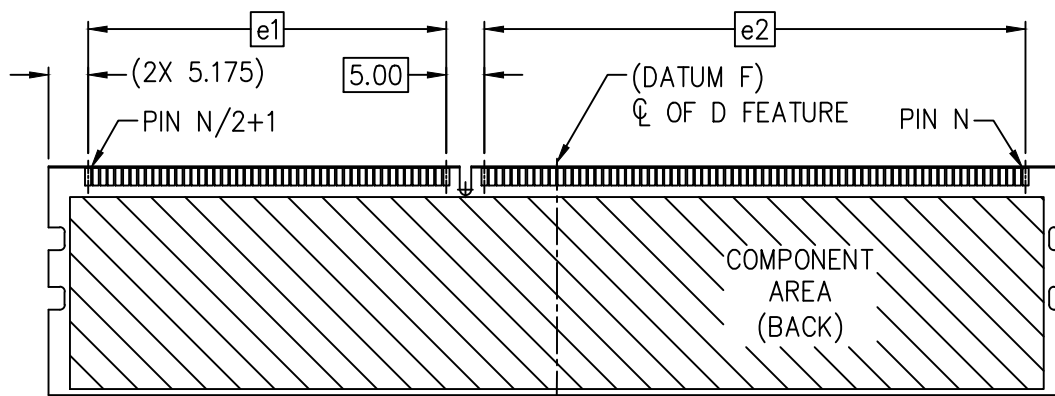
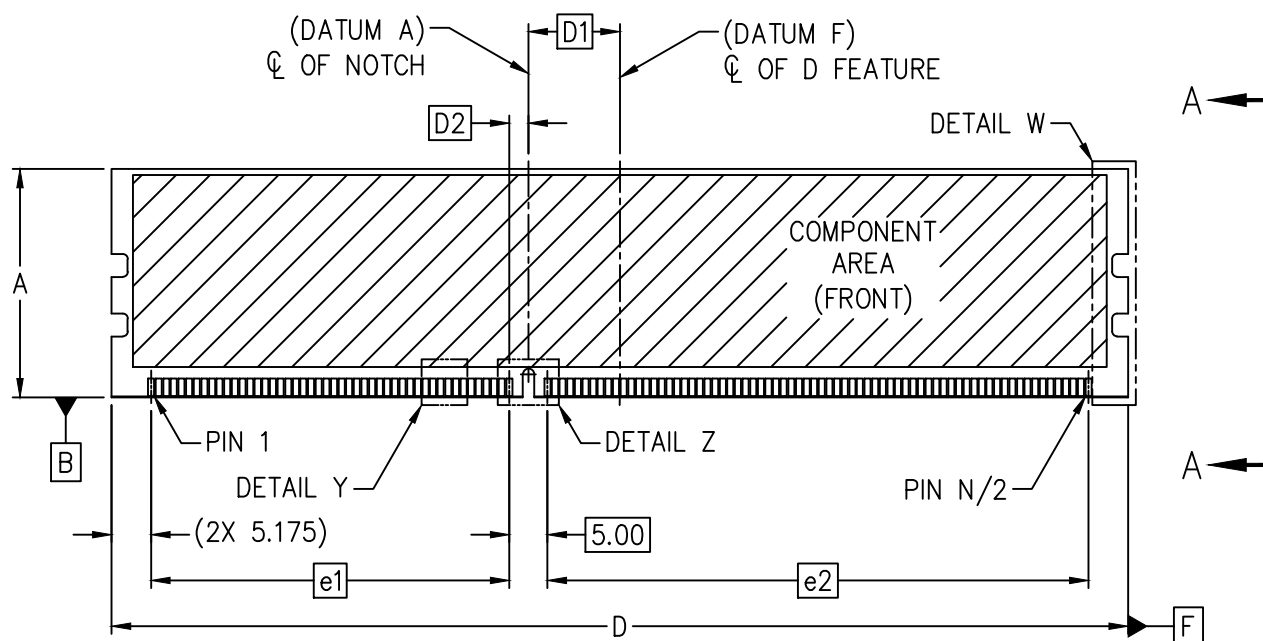




VARIATIONS AB, BB, CB, GB, HB

JEDEC SOLID STATE
PRODUCT OUTLINE
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AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY;
CHANGES ARE LIKELY TO OCCUR.

TITLE

240 PIN DDR3 DIMM,
1.00MM PITCH

PACKAGE DESIGNATOR

DIM

NUMBER

MO-269

ISSUE

DATE

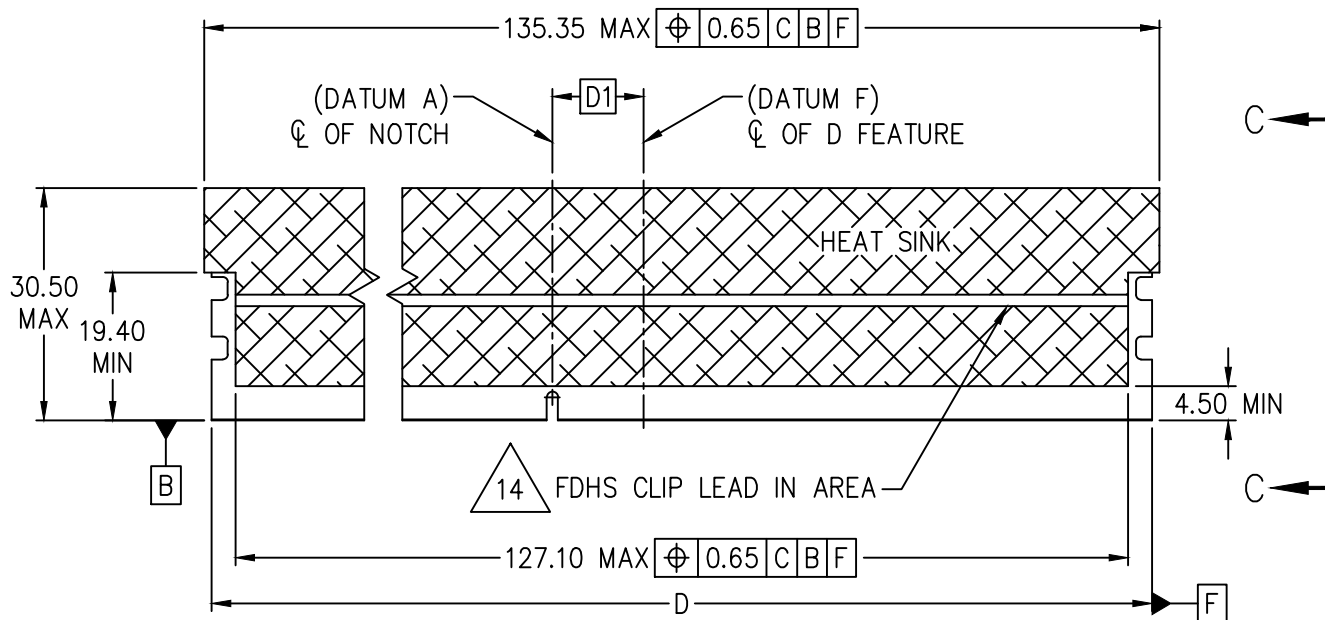
APR 2014

SHEET

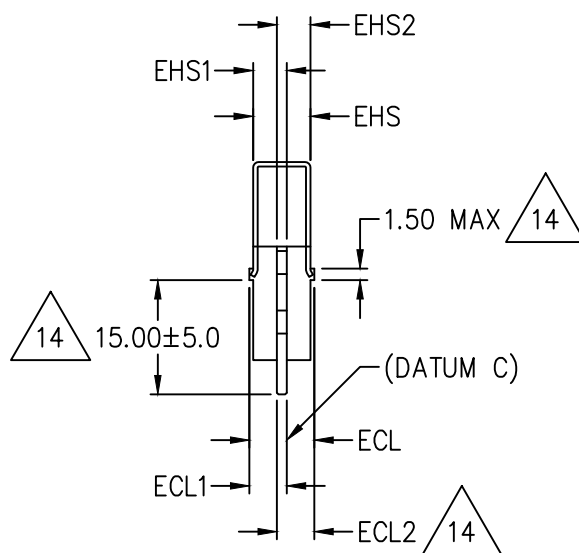
1 OF 28

Documents

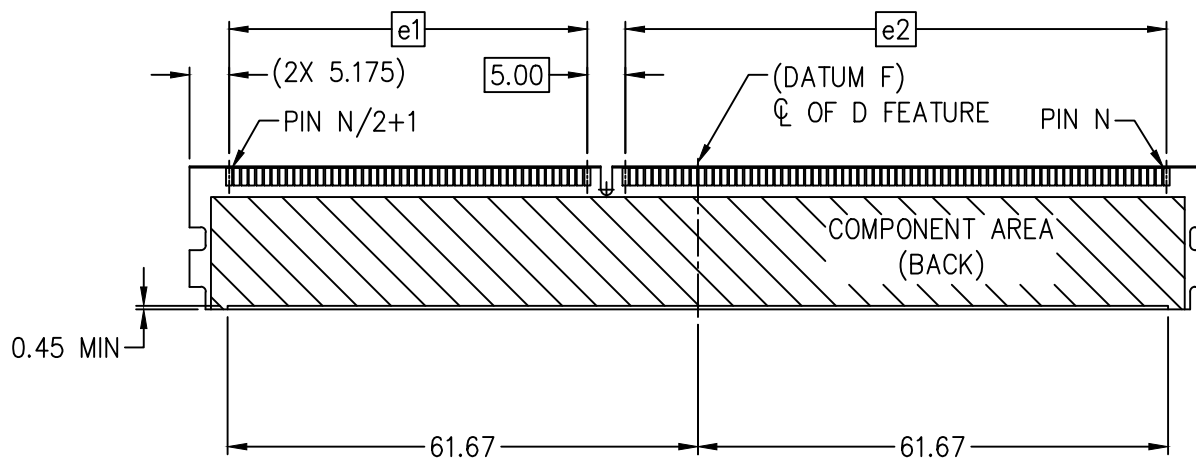
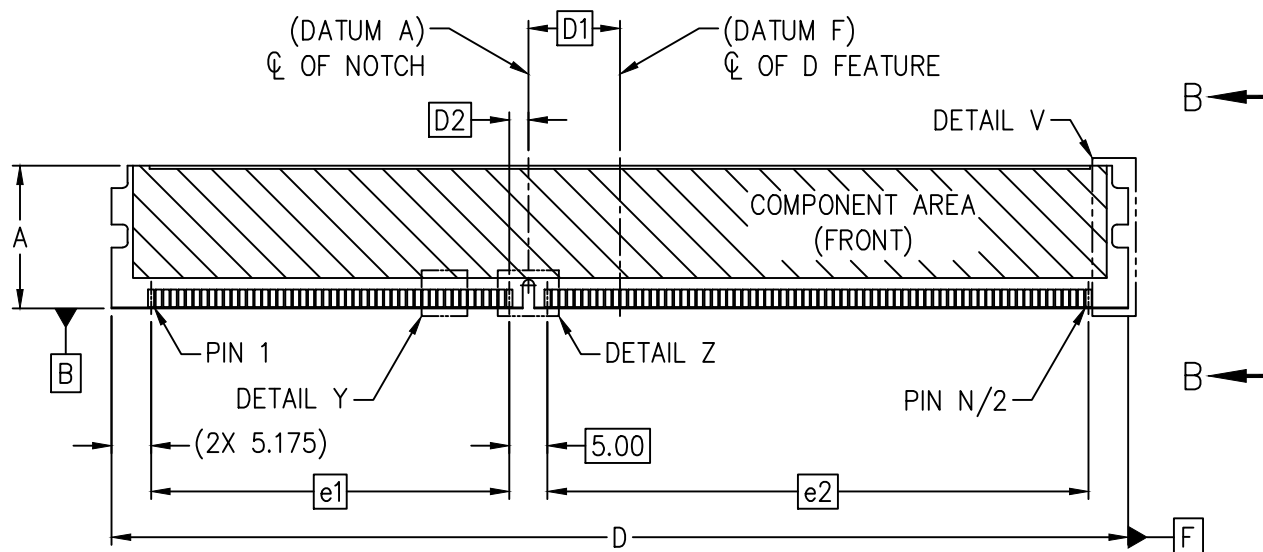
Document Sharing Hub



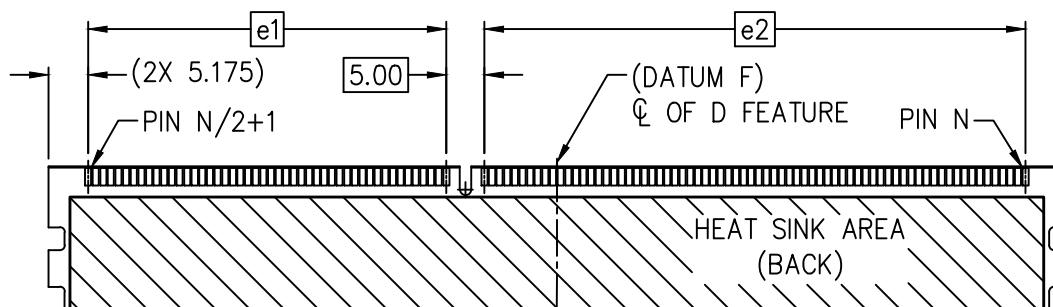
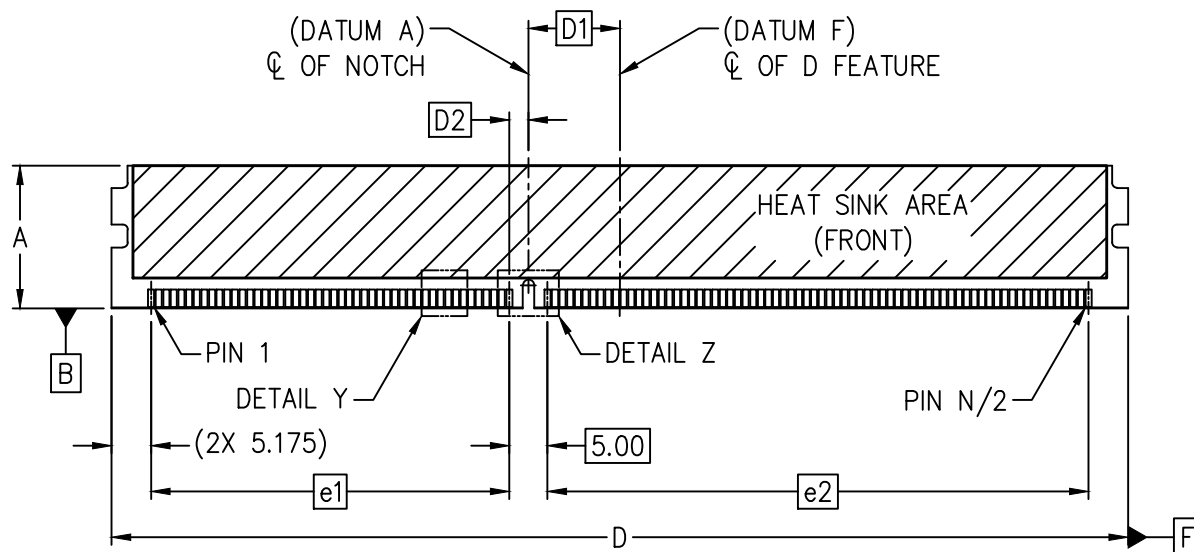
FDHS VOLUMETRIC KEEPIN
VARIATIONS HSAB, HSGB, HSHB, HSJB



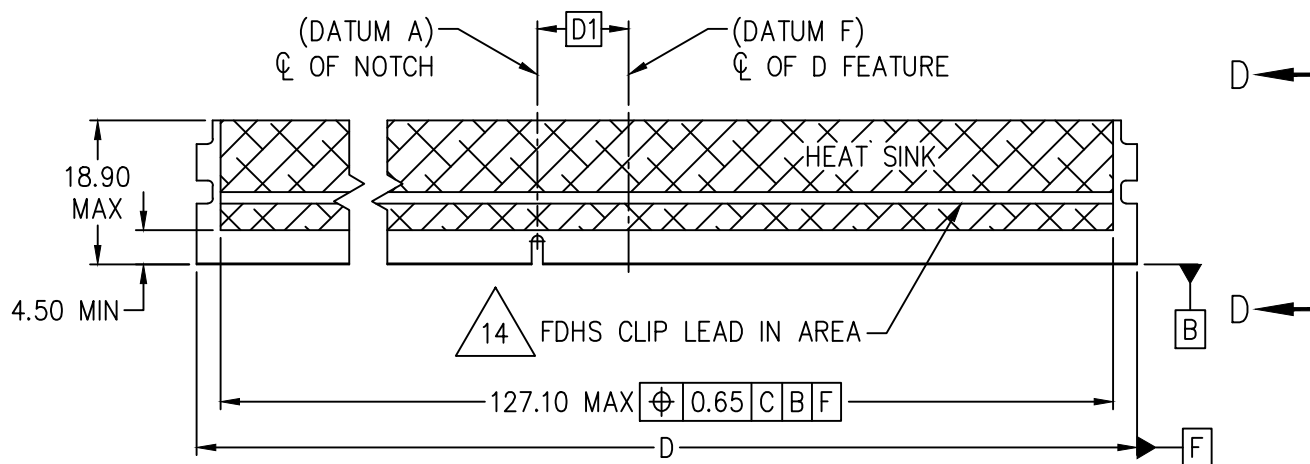
VIEW C-C



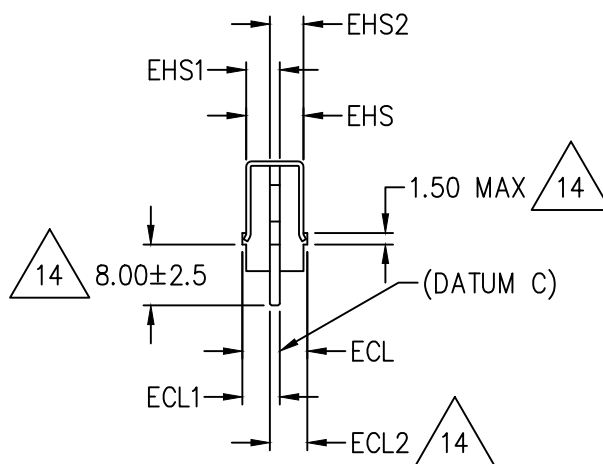
VARIATIONS DB, EB, FB WITHOUT HEAT SINK



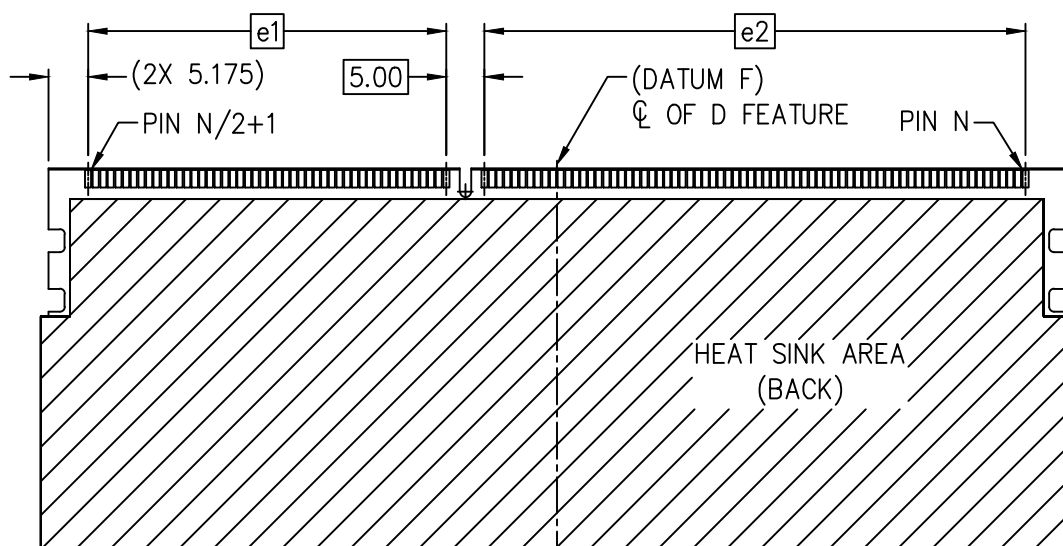
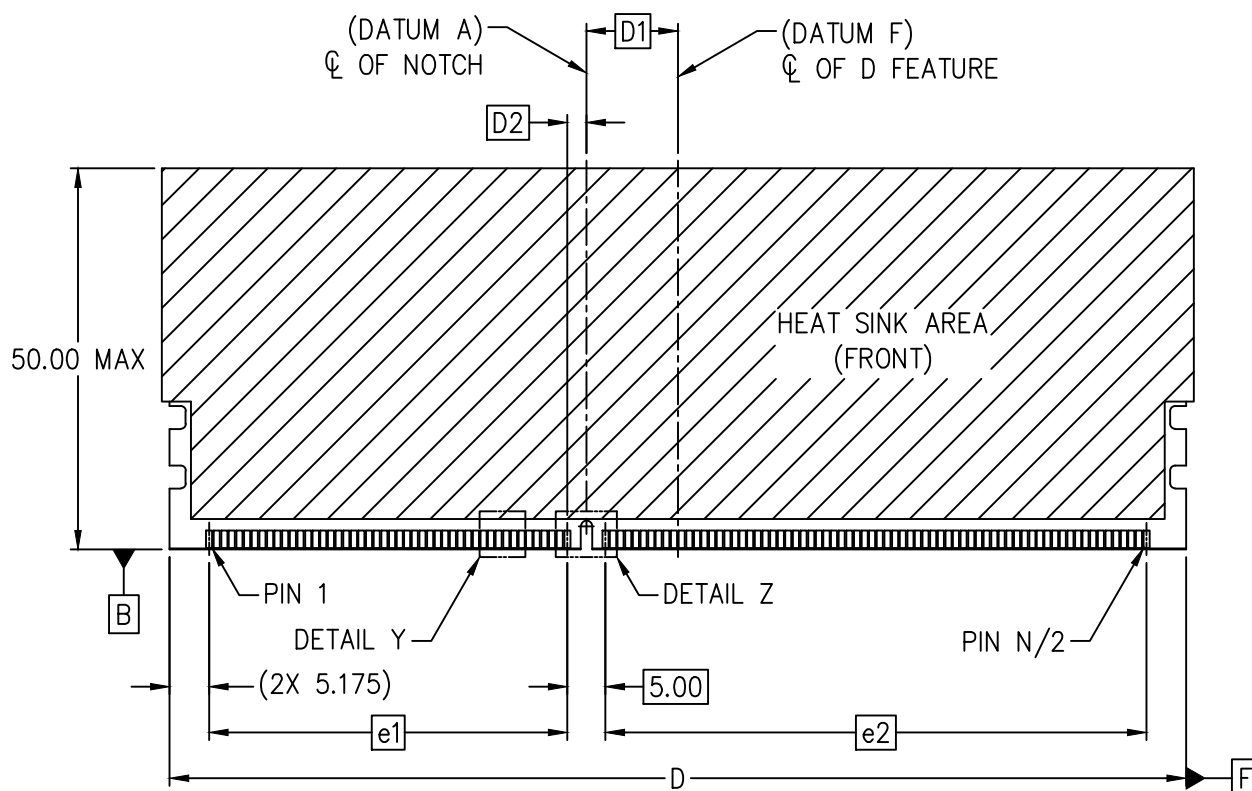
VARIATIONS HSDB, HSEB, HSFB



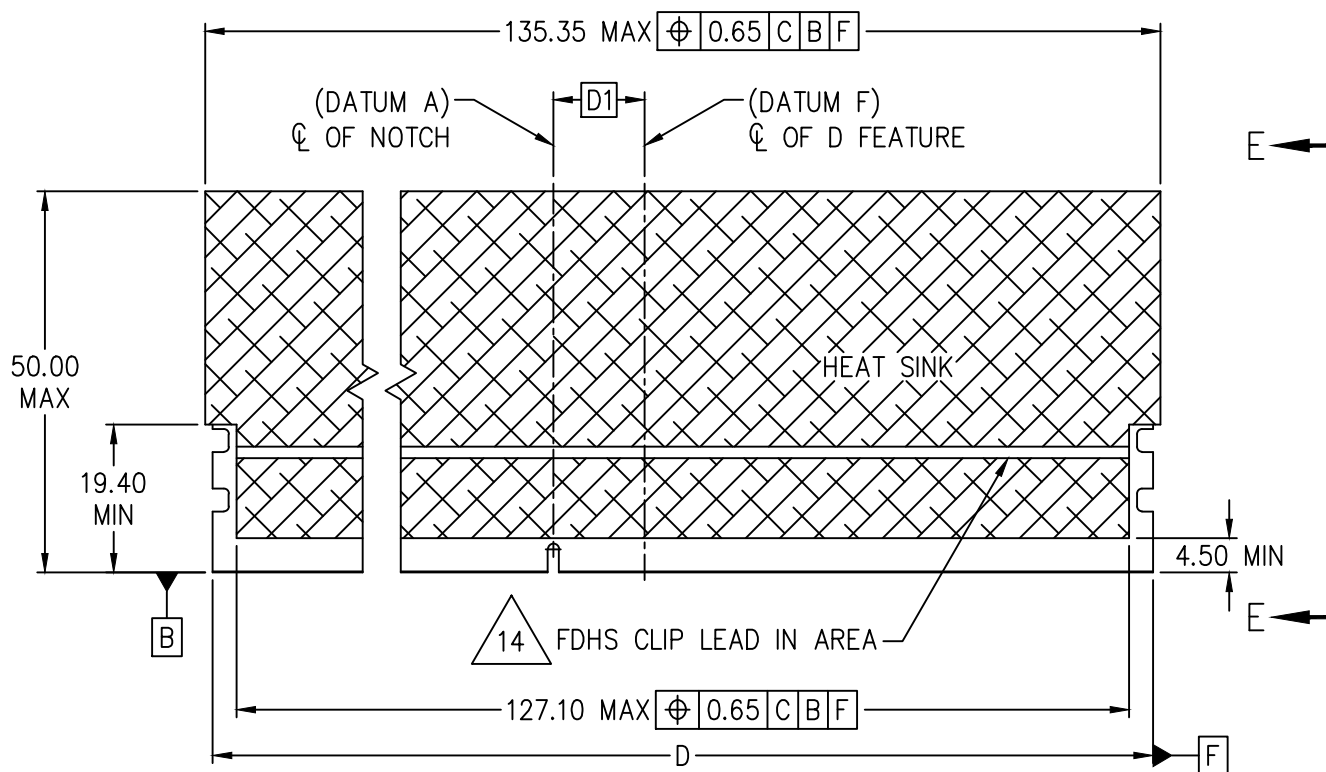
FDHS VOLUMETRIC KEEPIN FOR RDIMM
VARIATION HSDB



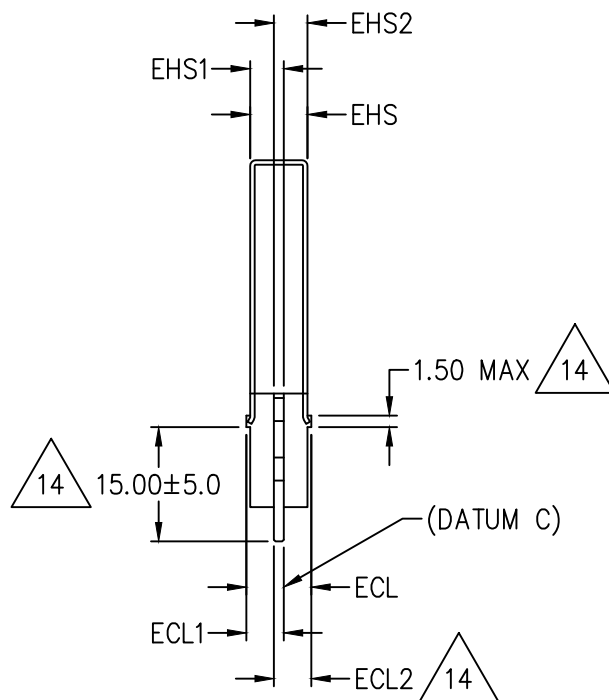
VIEW D-D



VARIATION THAB, USING VARIATIONS AB, BB, CB, GB, HB



FDHS VOLUMETRIC KEEPIN
VARIATION THAB, USING VARIATIONS AB, BB, CB, GB, HB



VIEW E-E

